

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HYUNG HWAN KIM</td> <td>12/24/2008</td> </tr> <tr> <td>KWANG KEE CHAE</td> <td>12/24/2008</td> </tr> <tr> <td>JONG GOO JUNG</td> <td>12/24/2008</td> </tr> <tr> <td>OK MIN MOON</td> <td>12/24/2008</td> </tr> <tr> <td>YOUNG BANG LEE</td> <td>12/24/2008</td> </tr> <tr> <td>SUNG EUN PARK</td> <td>12/24/2008</td> </tr> </tbody> </table>		Name	Execution Date	HYUNG HWAN KIM	12/24/2008	KWANG KEE CHAE	12/24/2008	JONG GOO JUNG	12/24/2008	OK MIN MOON	12/24/2008	YOUNG BANG LEE	12/24/2008	SUNG EUN PARK	12/24/2008
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RECEIVING PARTY DATA															
Name:	HYNIX SEMICONDUCTOR INC.														
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si														
City:	Kyoungki-do														
State/Country:	KOREA, REPUBLIC OF														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12345755</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12345755										
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CORRESPONDENCE DATA															
Fax Number:	(312)427-6663														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
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Email:	nicholas.kubacki@ladas.net														
Correspondent Name:	RICHARD J. STREIT														
Address Line 1:	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.														
Address Line 4:	CHICAGO, ILLINOIS 60604														
ATTORNEY DOCKET NUMBER:	CU-7235 WWP/NK														
NAME OF SUBMITTER:	Woochoon W. Park														

CH \$40.00 12345755

Total Attachments: 2
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UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNORS:

Name : Hyung Hwan KIM

Address : 702-1804, Hyundai 7-cha Apt., Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

Name : Kwang Kee CHAE

Address : 101-1301 Hansol Sol Park, Jeungpo-dong, Icheon-si, Gyeonggi-do, Korea

Name: Jong Goo JUNG

Address: 107-1001, Daemyeong Lake Ville, 946 Beonji, Yeongdeok-ri, Giheung-eup, Yongin-si, Gyeonggi-do, Korea

Name: Ok Min MOON

Address: #302, 360-7, Yuljeon-dong, Jangan-gu, Suwon-si, Gyeonggi-do, Korea

Name: Young Bang LEE

Address: #501, Taechang Villa B-dong, 594-24, Juan 2-dong 23/3, Nam-gu, Incheon-si, Gyeonggi-do, Korea

Name: Sung Eun PARK

Address: 6-1005, Useong Apt., Jamsil 7-dong, Songpa-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE
(TITLE)

and which is found in *(check one applicable item below)*

U.S. patent application executed on even date herewith


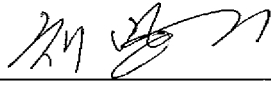
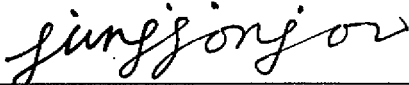
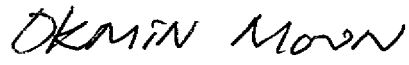
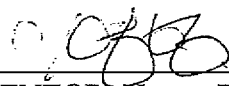

U.S. Application Serial No. _____ filed on _____

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

<u>December 24, 2008</u> Date	 INVENTOR: Hyung Hwan KIM
<u>December 24, 2008</u> Date	 INVENTOR: Kwang Kee CHAE
<u>December 24, 2008</u> Date	 INVENTOR: Jong Goo JUNG
<u>December 24, 2008</u> Date	 INVENTOR: Ok Min MOON
<u>December 24, 2008</u> Date	 INVENTOR: Young Bang LEE
<u>December 24, 2008</u> Date	 INVENTOR: Sung Eun PARK

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